

New materials for memristive switching

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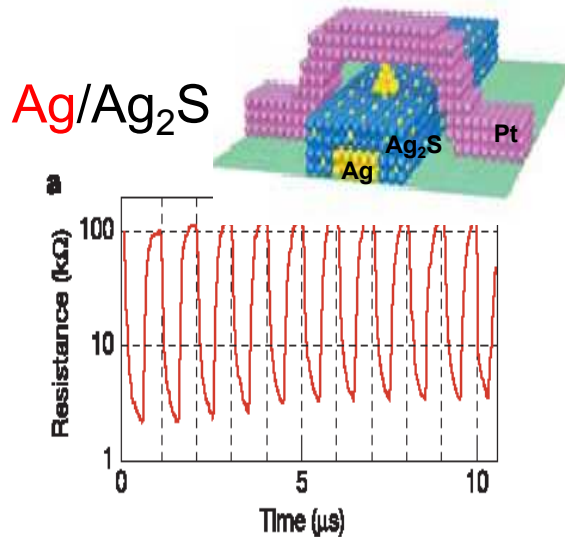
University of California, Santa Cruz



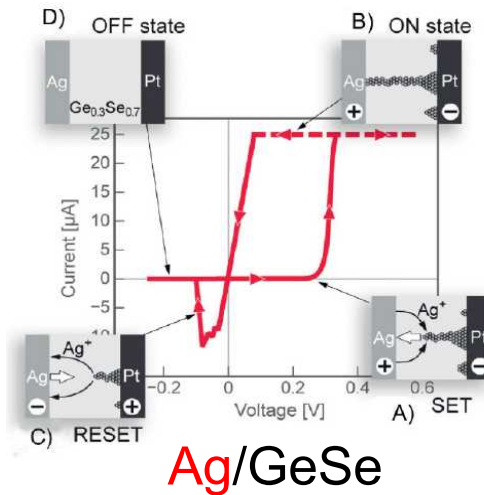
Outline

- 1. Introduction: new switching materials**
- 2. Non-oxide switching materials**
- 3. Metal doped Switching Materials**
- 4. Summary**

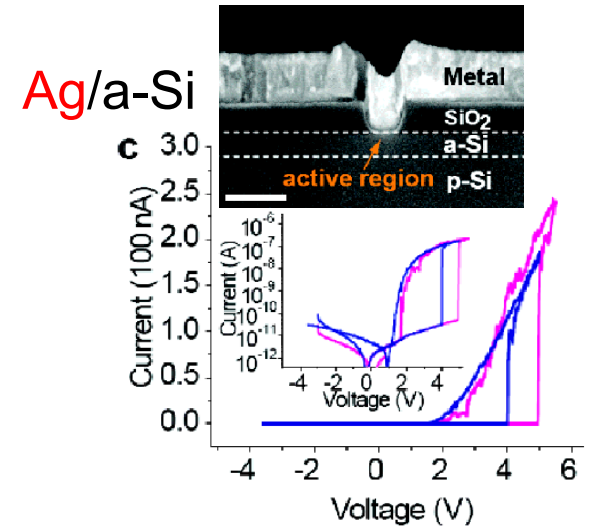
Introduction – ionic switching materials



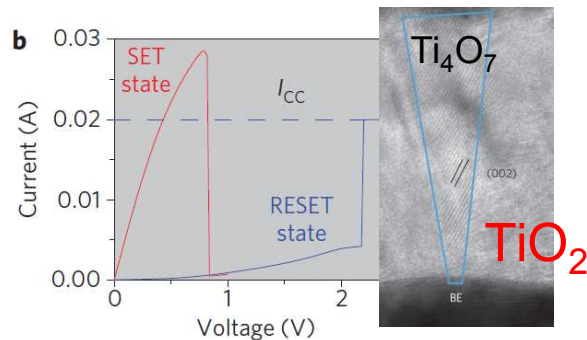
Terabe *et al.* Nature 433,47 (2005)



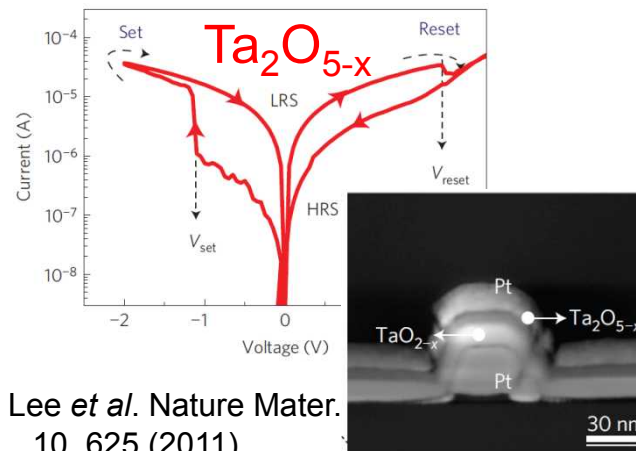
Waser *et al.* Adv. Mat. 21, 2632 (2009)



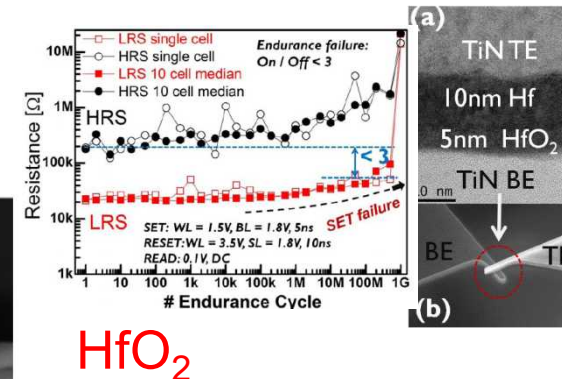
Jo & Lu, Nano Lett. 8, 392 (2008)



Kwon *et al.* Nature Nanotechnol. 5, 148 (2010)



Lee *et al.* Nature Mater. 10, 625 (2011)



Chen *et al.* '2012 IEDM

Summary of Anion based switching materials – valence change switching

Most are oxides

Very few non-oxides

Insulators	Bottom Electrode	Top electrode	Switching mode	reference
MgO	Pt	Pt	Unipolar	1
TiOx	Ru, Pt	Al, Pt	Non/Uni/Bipolar	2, 3
ZrO ₂	p ⁺ -Si, n ⁺ -Si	Pt, Cr	Uni/Bipolar	4-6
HfO ₂	TiN	TiN	Bipolar	7
VO ₂	N/A	N/A	Threshold	8, 9
NbO ₂	p ⁺ -Si	Pt	Unipolar	10
TaO ₂	Pt, Ta	Pt, Ta	Bipolar	11, 12
CrO ₂	TiN	Pt	Bipolar	13
MoO ₃	Pt	Pt-Ir	Uni/Bipolar	14
WO ₃	W, FTO	TiN, Au	Bipolar	15, 16
MnO ₂	Pt	Al, TiN	Bipolar	17, 18
FeO ₂	Pt	Pt	Non/Bipolar	19, 20
CoO ₂	Pt	Pt	Nonpolar	21
NiO ₂	Pt	Pt	Nonpolar/Threshold	22, 23
CuO ₂	TiN, TaN, SRO, Pt	Pt	Bipolar	24
ZnO ₂	Pt, Au	TiN, Ag	Bipolar	25-27
AlO ₂	Ru, Pt	Pt, Ti	Unipolar/Bipolar	28, 29
GaO ₂	ITO	Pt, Ti	Bipolar	30
SiO ₂	Poly-Si, TiW	Poly-Si, TiW	Unipolar	31
SiO ₂ N _y	W	Cu	Bipolar	32
GeO ₂	ITO, TaN	Pt, Ni	Bipolar	33, 34
SnO ₂	Pt	Pt	Unipolar	35
BiO ₂	Bi	W, Re, Ag, Cu	Bipolar	36
SbO ₂	Pt	Sb	Unipolar/Bipolar	37
SmO ₂	TiN	Pt	Bipolar	38
GdO ₂	Pt	Pt	Unipolar	39
YO ₂	Al	Al	Unipolar	40
CeO ₂	Pt	Al	Bipolar	41
EuO ₂	TaN	Ru	Uni/Bipolar	42, 43
PrO ₂	TaN	Ru	Bipolar	42, 43
ErO ₂	TaN	Ru	Unipolar	42, 43
DyO ₂	TaN	Ru	Unipolar	42, 43
NdO ₂	TaN	Ru	Unipolar	42, 43
Ba _{0.7} Sr _{0.3} TiO ₃	SrRuO ₃	Pt, W	Bipolar	44
SrTiO ₃	SrRuO ₃ , Au, Pt	Au, Pt	Bipolar	45
SrZrO ₃	SrRuO ₃	Au	Bipolar	46
BiFeO ₃	LaNiO ₃	Pt	Bipolar	47
Pr _{0.7} Ca _{0.3} MnO ₃	YBCO, Pt, LaAlO ₃	Ag	Bipolar	48
La _{0.7} Sr _{0.3} FeO ₃	Au	Al	Bipolar	49
Pr ₁ La _{0.625} Ca _{0.175} MnO ₃	Ag	Ag	Bipolar	50
Nitrides (AlN)	Al, TiN, Pt	Al, TiN, Pt	Bipolar	51
Telluride (ZnTe)	Si	Au	Bipolar	52
selenide (ZnSe)	p ⁺ -Ge	In, In-Zn	Bipolar	53
Polymers	Al, ITO, Cu	Al, ITO, Cu	Bipolar	54, 55

Even though non-oxide materials: 1) bigger pool
2) may even have better performance

New materials

May provide

- 1) Better compatibility with industry electrode materials^[1]
- 2) Better control of conduction filament formation.^[2]

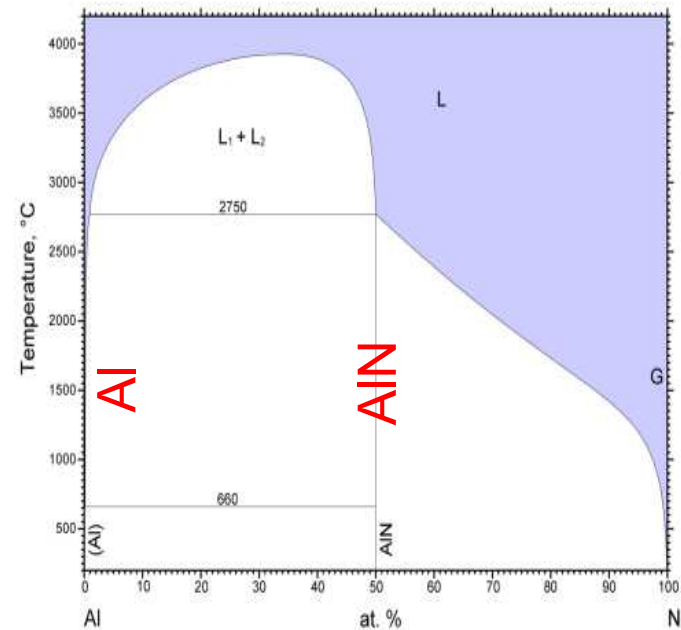
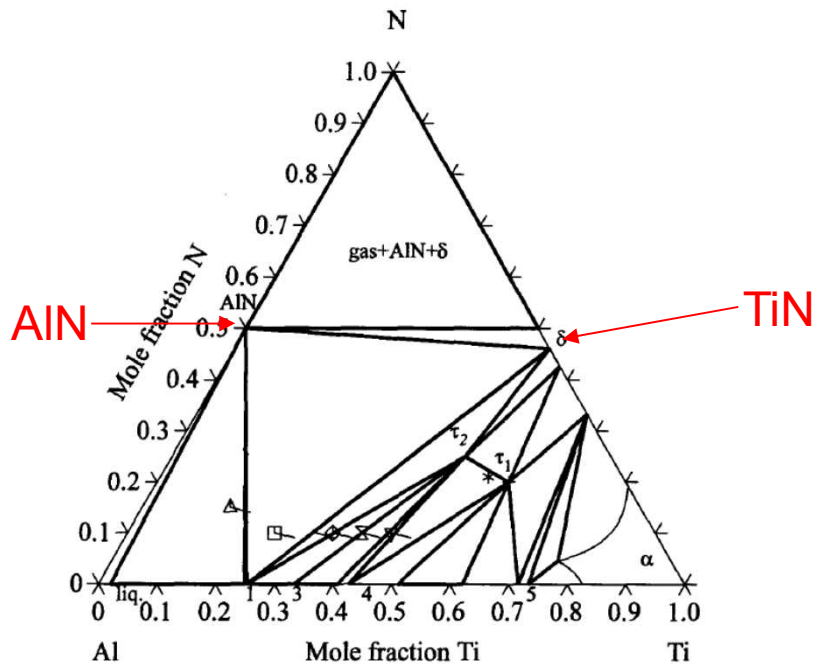
[1] **B. J. Choi** et al. *Appl. Phys. A*, **109**, 1 (2012)

[2] **B. J. Choi** et al. *Nano Lett.* **13**, 3213 (2013)

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MOTIVATIONS: A Full - Nitride Memristor



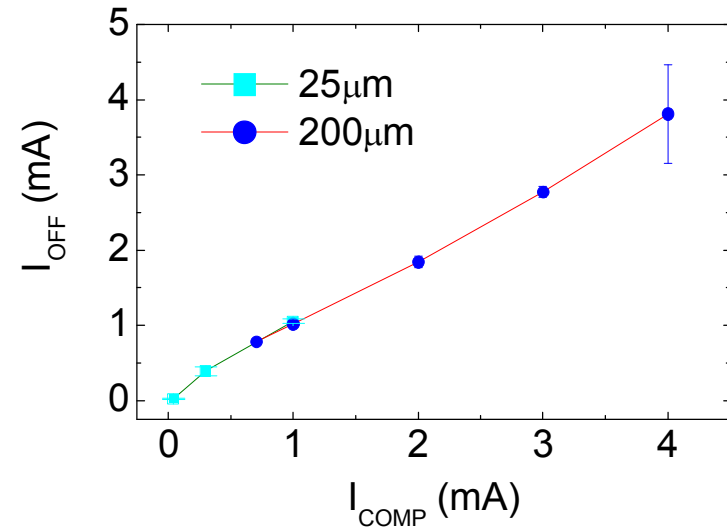
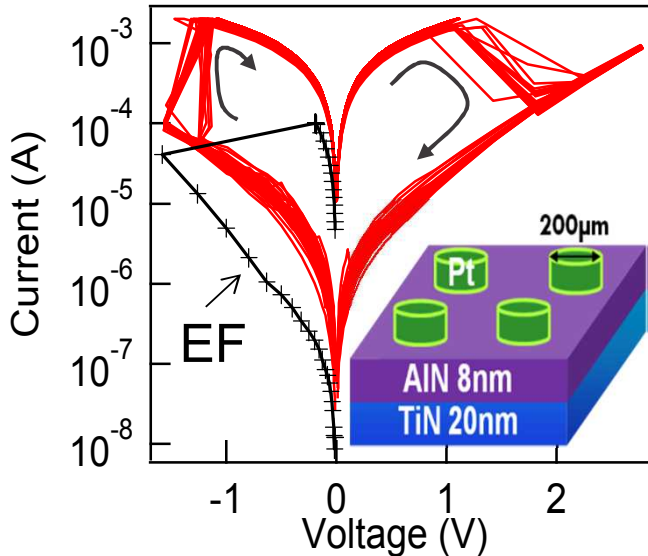
TiN/AlN structure

- 1) TiN: fab preferred material
- 2) AlN and TiN: thermodynamic equilibrium between AlN and TiN
- 3) TiN: a large solubility of N $\rightarrow$ perfect electrode (serving as N reservoir)
- 4) AlN: only two stable solid phases $\rightarrow$ perfect switching material (a conducting phase + an insulating phase, same as Ta-O)

Device performance: repeatable

AlN memristor

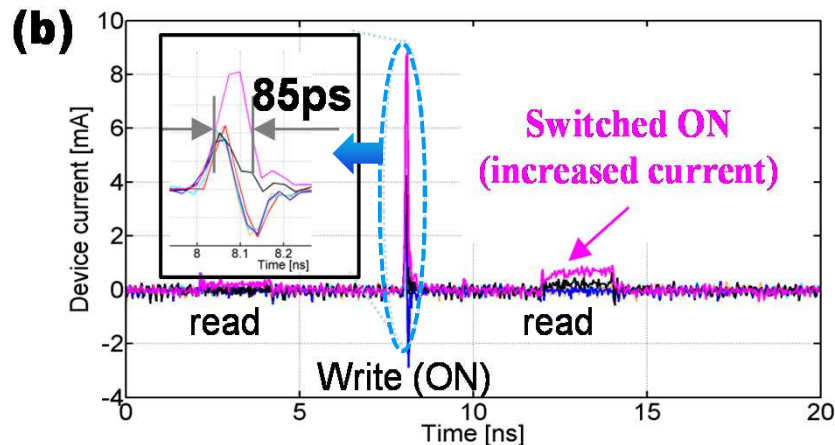
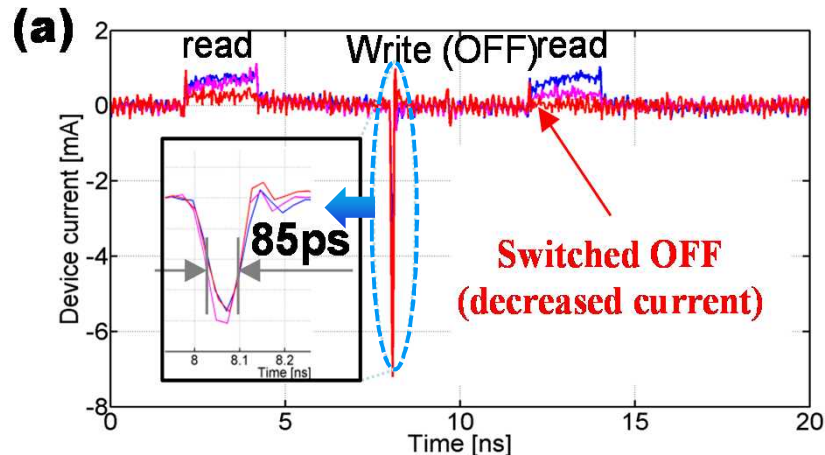
100 consecutive cycles



- Nitride memristors reported
- Stable and reproducible switching was observed after electro-forming
- Compliance current (I_{comp}) defines device resistance and I_{OFF}

Device performance: ultra-fast real-time switching

Bipolar device ($2\mu\text{m} \times 2\mu\text{m}$) – OFF & ON switching



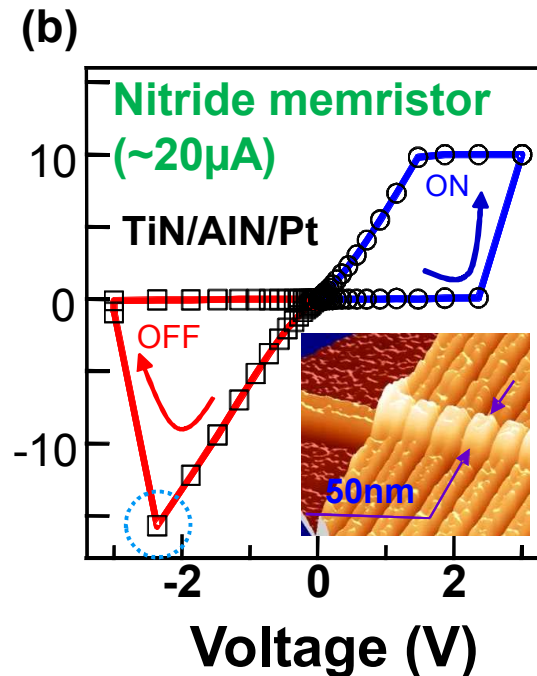
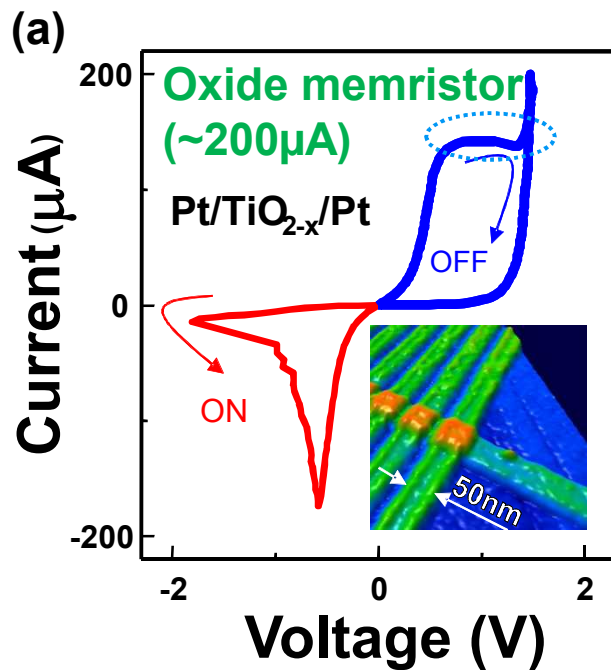
Pulse sequence	Quasi-DC device resistance [k Ω]
Initial	0.73
#3 (-2.0 V / 86 ps)	97.83 (OFF)

Initial	83 M Ω
#6 (+2.1 V / 87 ps)	2.56 k Ω (ON)
#7 (+2.1 V / 87 ps)	0.73 k Ω (ON)

- Sub-100ps switching observed
- Strongly nonlinear switching dynamics

Device performance: scalability and low energy

50nm x 50nm nanodevice

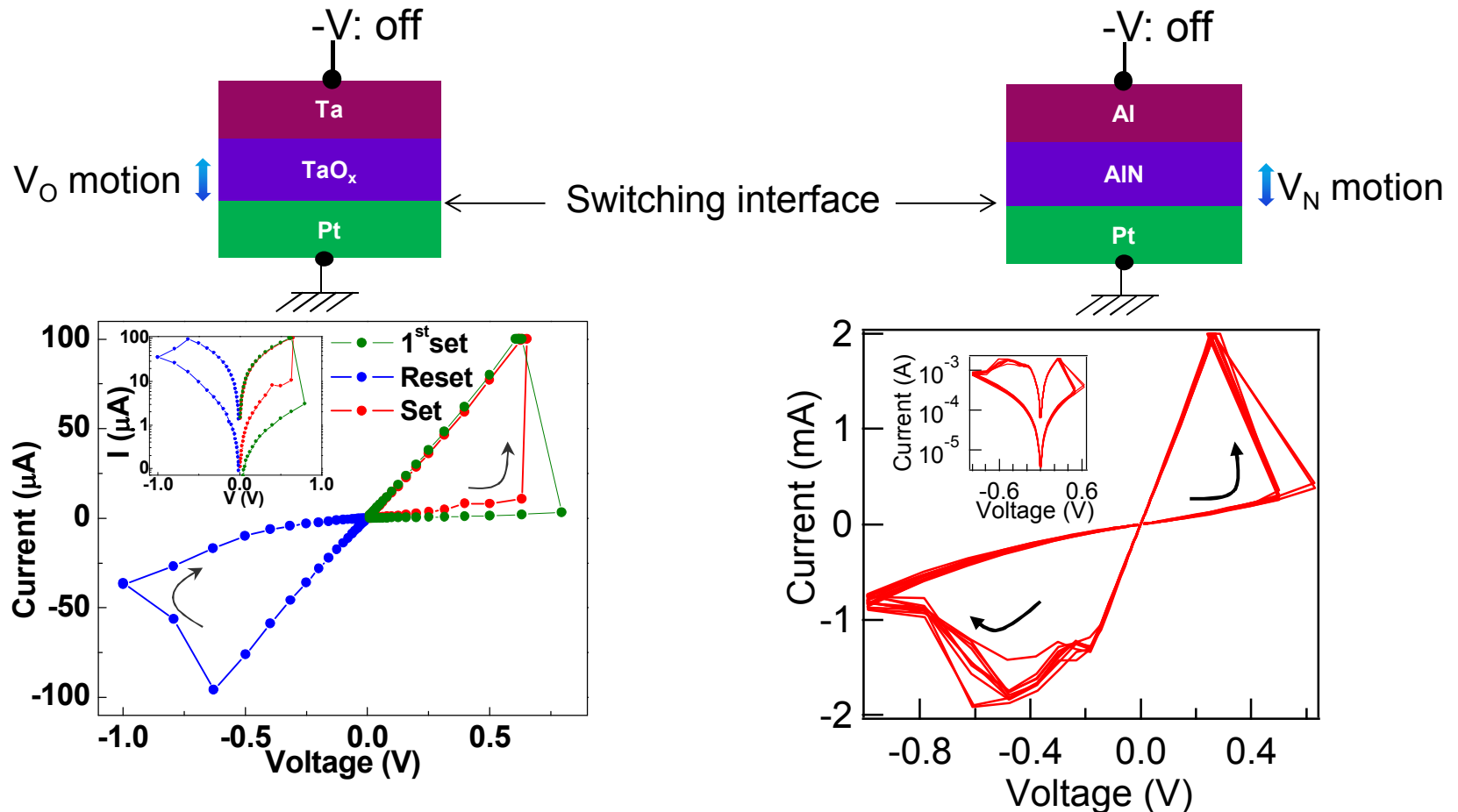


Low-energy device:

Lower current than TiOx and even TaOx

- OFF-switching current 10~20 μA
- High ON/OFF ratio (>100)

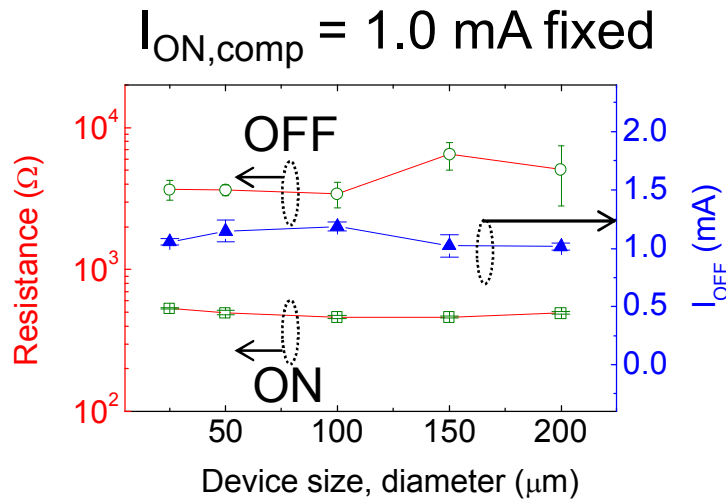
Mechanism: Analogous to oxide



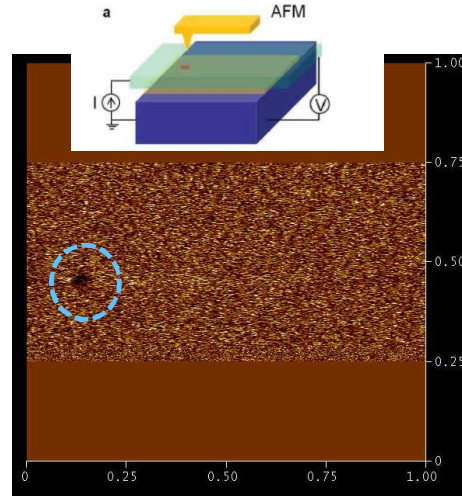
Inert interface favorable!

Mechanism: Localized channels

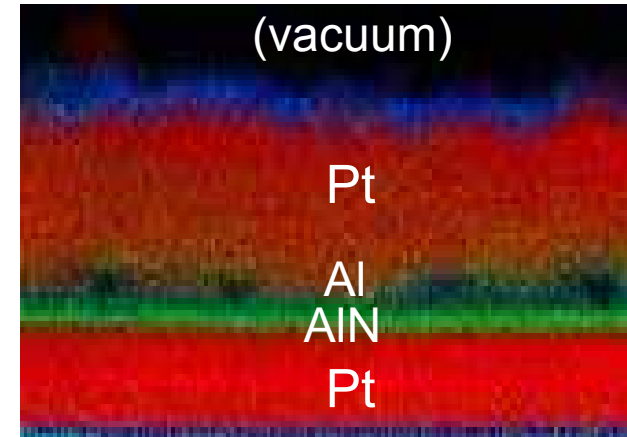
Various evidences



Irrelevance to
area (Electrical
test)

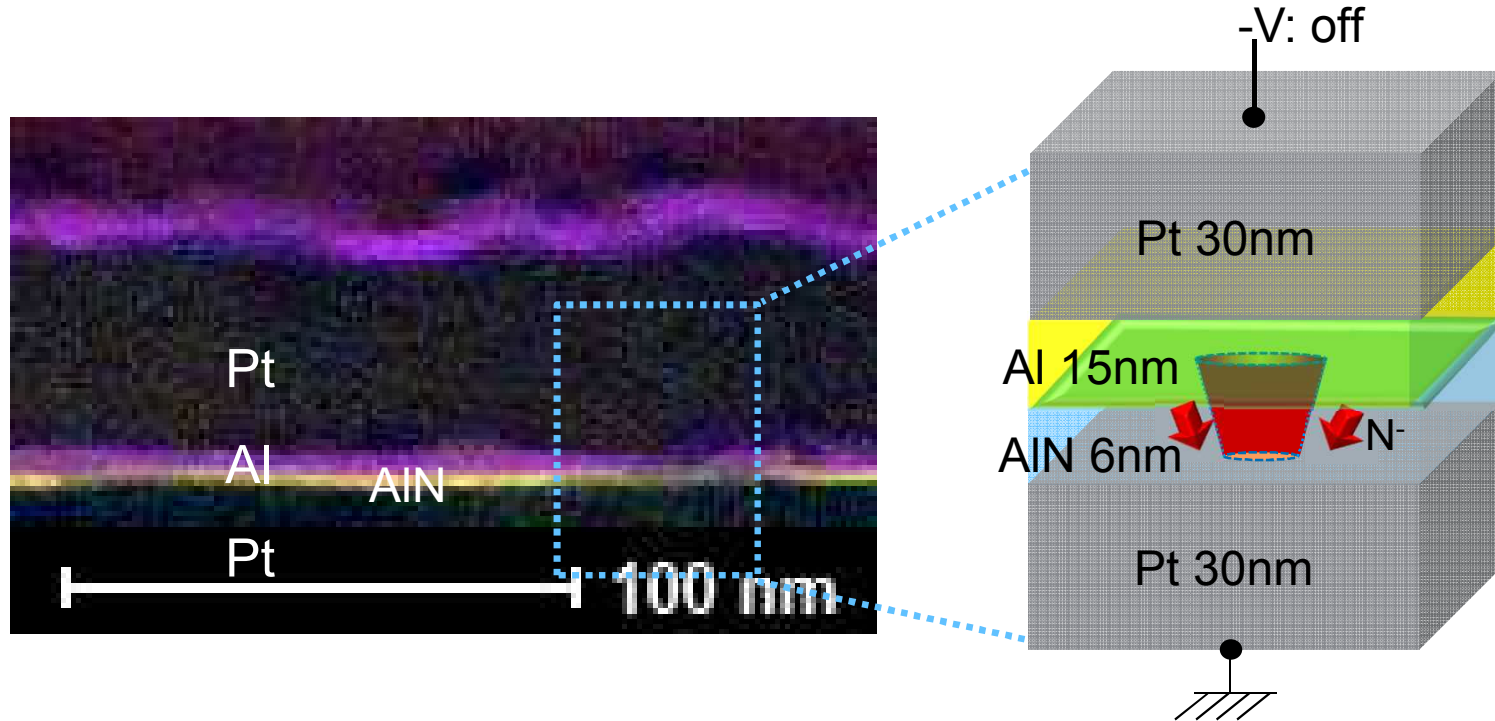


Localized
conducting region
detected
(PMCM)



Chemical change
(TEM-EDS)

Mechanism: Al(N) channels



- Strongly localized heating
- Formation of N-deficient Al(N) $\rightarrow$ Localized channel

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Engineered Materials



US008415652B2

(12) **United States Patent**
Yang et al.

(10) **Patent No.:** **US 8,415,652 B2**
(45) **Date of Patent:** **Apr. 9, 2013**

(54) **MEMRISTORS WITH A SWITCHING LAYER**
COMPRISING A COMPOSITE OF MULTIPLE
PHASES

FOREIGN PATENT DOCUMENTS
WO 2009114796 A1 9/2009

(75) Inventors: **Jianhua Yang**, Palo Alto, CA (US);
Gilberto Ribeiro, Menlo Park, CA (US);
R. Stanley Williams, Portola Valley, CA (US)

OTHER PUBLICATIONS

J. Yang et al., "The Mechanism of Electroforming of Metal Oxide Memristive Switches", Research Paper, Information and Quantum Systems Lab, Hewlett-Packard Laboratories; Department of Physics and Astronomy, University of California, Published 2009.
T. Driscoll et al., "S. Phase-Transition Driven Memristive System", Research Paper, University of California, San Diego, physics department; MIT—Device Team, ETRI, Daejeon 305-350, Republic of Korea.

(73) Assignee: **Hewlett-Packard Development Company, L.P.**, Houston, TX (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 220 days.

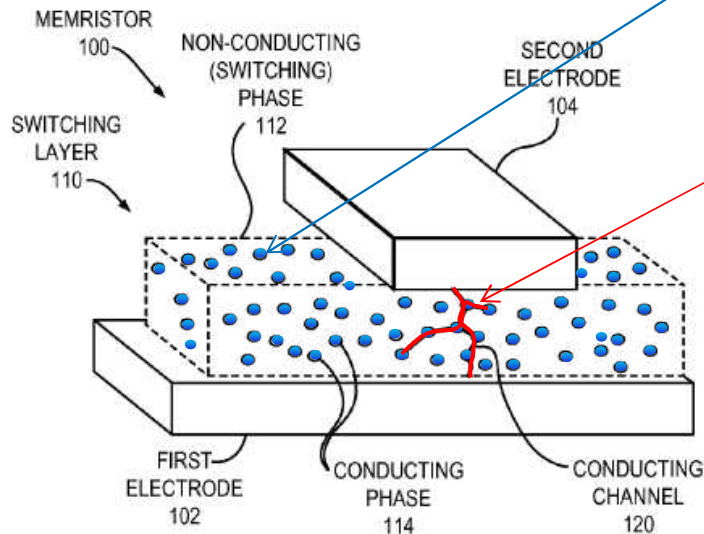
* cited by examiner

(21) Appl. No.: **12/819,763**

(22) Filed: **Jun. 21, 2010**

Primary Examiner — Jami M Valentine

(74) Attorney, Agent, or Firm — David W. Collins



Origin:

Different switching channels in different devices.

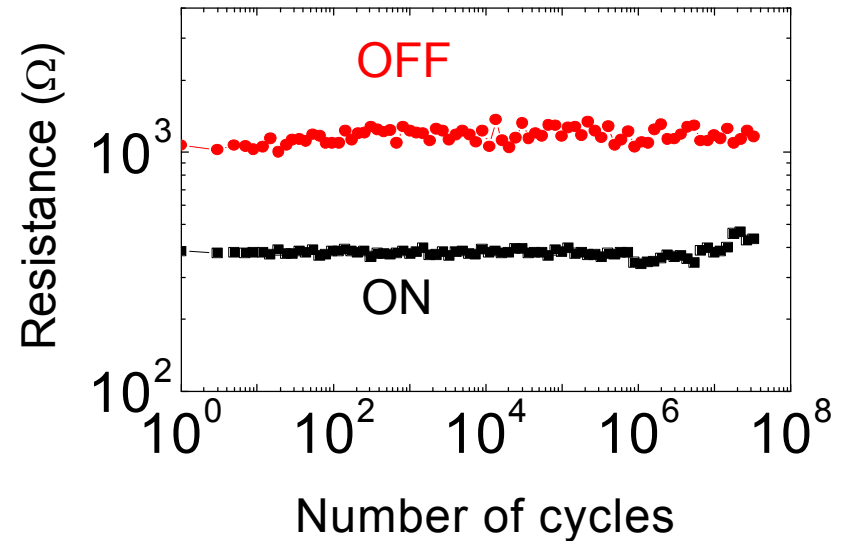
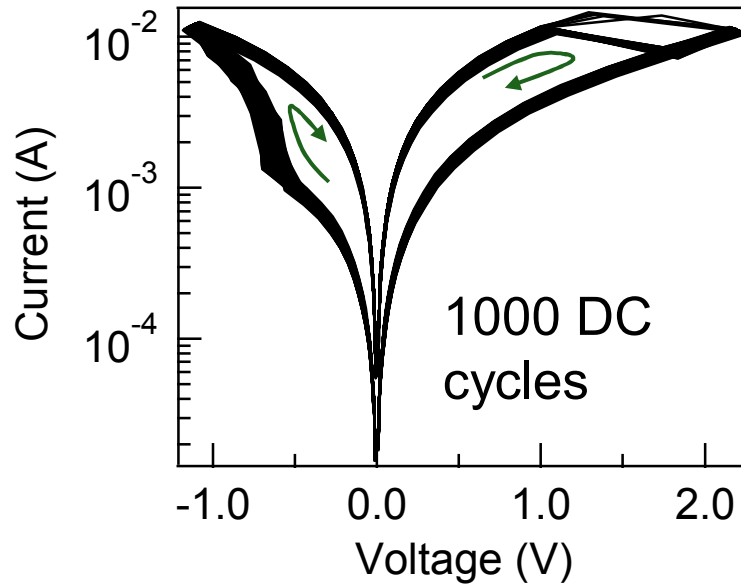
Solution:

Plant similar seeds (nanoclusters) of switching channels in different devices

facilitate similar switching channels formed in every device.



Device performance: Reliable

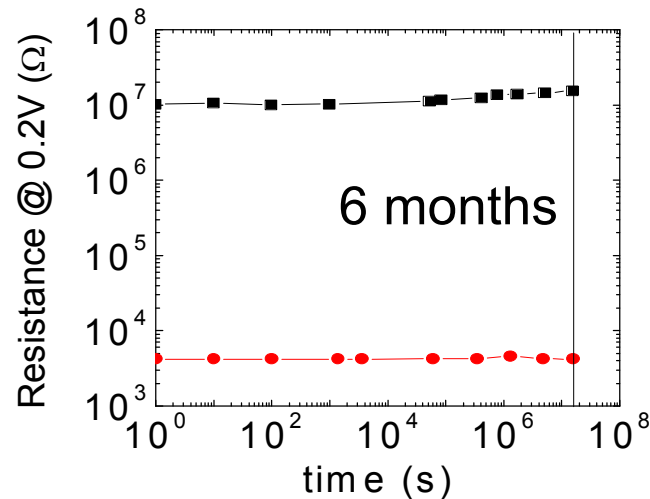
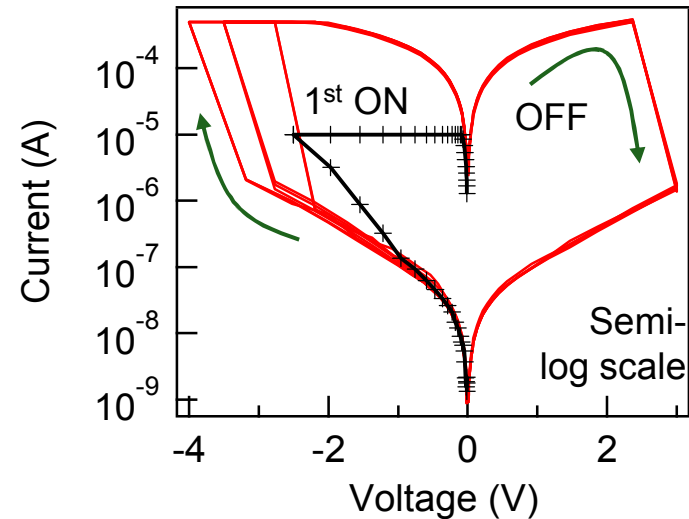
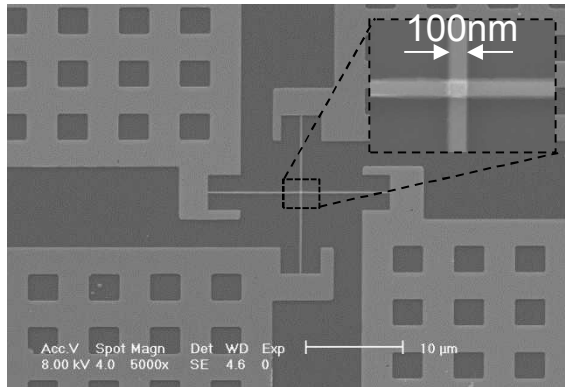


- Excellent uniformity and high durability
- Much reliable than binary oxide switching

B. J. Choi et al. *Adv. Mater.* **23**, 3847 (2011)

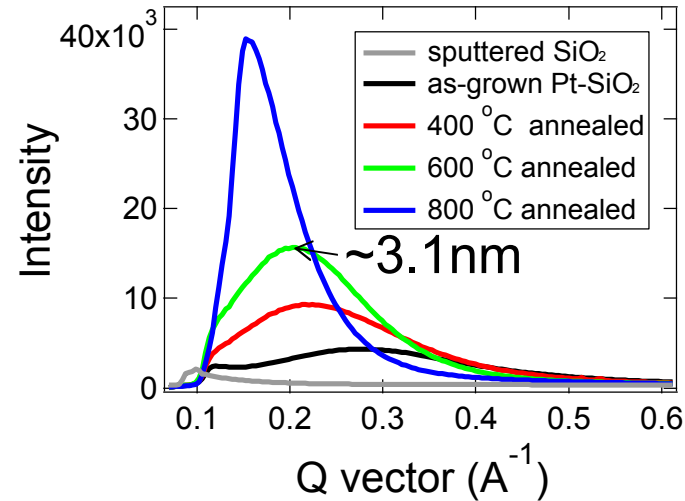
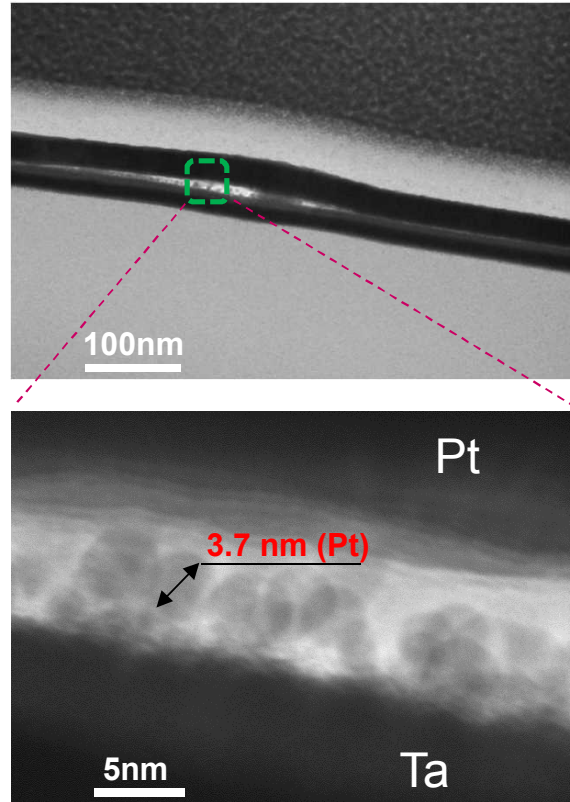
B. J. Choi et al. *Nano Lett.* **13**, 3213 (2013)

Device performance: Scalable



- Scalability proved down to $(100\text{nm})^2$
- Uniform, high ON/OFF ratio
- No change up to 6 months

Mechanism: Pt templated memristive switching



- Pt nanoparticle → rounder and bigger
- Joule heating and electric field
- Ionic switching effects are highly probable

Summary

– *New switching materials for memristive switching*

- *Nitride memristors* demonstrated
- Fast switching (**~85ps**), **scalability** (50nm) with **low energy** consumption observed
- Switching at the **more inert interface** with localized **conducting channel**
- Switching interface is **O-free** after forming → **Nitride Memristor!**
- *ASM* (Artificial Switching Materials) are demonstrated
- Highly reproducible and uniform switching is observed
- Scaling with excellent device yield
- Possibly ANY metal into ANY insulator

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